

# Global Temporary Wafer Debonding System Supply, Demand and Key Producers, 2023-2029

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## Abstracts

Thin wafer handling will enjoy increased importance in the coming years, but as chips get thinner and wafer diameter increases, thinning/handling procedures are required. This implies development in wafer thinning, wafer dicing and wafer temporary bonding. Temporary bonding implies know-how in process and chemistry, and an understanding of the final application requirements. Temporary bonding is a complex technology, requiring an interface material (sometimes called the “Magic” material) that is strong enough to withstand post-processing but which can be easily removed afterwards. As the main concern for temporary bonding materials (wax, tape or glue) is temperature stability, the material must be strong enough to withstand processing steps (metallization, etching, grinding). Another issue is the choice of carrier material. Carrier lifetime depends on its capability to withstand steps such as grinding, etc., and carrier lifetime should be at least tens of times.

This report studies the global Temporary Wafer Debonding System production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Temporary Wafer Debonding System, and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of Temporary Wafer Debonding System that contribute to its increasing demand across many markets.

The global Temporary Wafer Debonding System market size is expected to reach \$ million by 2029, rising at a market growth of % CAGR during the forecast period (2023-2029).

## Highlights and key features of the study

Global Temporary Wafer Debonding System total production and demand, 2018-2029, (K Units)

Global Temporary Wafer Debonding System total production value, 2018-2029, (USD Million)

Global Temporary Wafer Debonding System production by region & country, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Temporary Wafer Debonding System consumption by region & country, CAGR, 2018-2029 & (K Units)

U.S. VS China: Temporary Wafer Debonding System domestic production, consumption, key domestic manufacturers and share

Global Temporary Wafer Debonding System production by manufacturer, production, price, value and market share 2018-2023, (USD Million) & (K Units)

Global Temporary Wafer Debonding System production by Type, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Temporary Wafer Debonding System production by Application production, value, CAGR, 2018-2029, (USD Million) & (K Units)

This reports profiles key players in the global Temporary Wafer Debonding System market based on the following parameters – company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include EV Group, SUSS MicroTec, Tokyo Electron, Cost Effective Equipment, Micro Materials, Dynatech, ERS electronic GmbH, Brewer Science and Kingyup Enterprises, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals, COVID-19 and Russia-Ukraine War Influence.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Temporary Wafer Debonding System market

## Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (K Units) and average price (US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

## Global Temporary Wafer Debonding System Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

## Global Temporary Wafer Debonding System Market, Segmentation by Type

Chemical Debonding

Hot Sliding Debonding

Mechanical Debonding

Laser Debonding

## Global Temporary Wafer Debonding System Market, Segmentation by Application

MEMS

Advanced Packaging

CMOS

Others

#### Companies Profiled:

EV Group

SUSS MicroTec

Tokyo Electron

Cost Effective Equipment

Micro Materials

Dynatech

ERS electronic GmbH

Brewer Science

Kingyoup Enterprises

#### Key Questions Answered

1. How big is the global Temporary Wafer Debonding System market?
2. What is the demand of the global Temporary Wafer Debonding System market?
3. What is the year over year growth of the global Temporary Wafer Debonding System market?

4. What is the production and production value of the global Temporary Wafer Debonding System market?
5. Who are the key producers in the global Temporary Wafer Debonding System market?
6. What are the growth factors driving the market demand?

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